

## CLAIMS

What is claimed is:

- 5 1. A chip type semiconductor device comprising:  
an insulating substrate;  
first and second conductive land areas which are formed  
on said insulating substrate and which are electrically coupled  
with each other;  
10 a conductive post formed on said first conductive land  
area;  
a semiconductor pellet which has electrodes on both  
sides thereof and which is mounted on said second conductive  
land area, said electrode on one side of said semiconductor  
15 pellet being coupled onto said second conductive land area and  
said electrode on the other side of said semiconductor pellet  
having an external electrode electrically coupled thereto; and  
encapsulation resin portion which encapsulates a main  
area of said insulating substrate including said conductive post  
20 and said semiconductor pellet, wherein top portions of said  
conductive post and said external electrode electrically coupled  
to said semiconductor pellet being exposed from said  
encapsulation resin portion.
- 25 2. A chip type semiconductor device as set forth in claim 1,  
wherein said conductive post and said external electrode  
electrically coupled to said semiconductor pellet are disposed  
such that top surfaces of said conductive post and said external  
electrode become approximately coplanar with each other.

3. A chip type semiconductor device as set forth in claim 1,  
wherein said conductive post is a column shaped conductive  
block member.
- 5 4. A chip type semiconductor device as set forth in claim 3,  
wherein said column shaped conductive block member is  
coupled to said first conductive land area via conductive  
adhesive.
- 10 5. A chip type semiconductor device as set forth in claim 3,  
wherein said column shaped conductive block member is  
coupled to said first conductive land area by using ultrasonic  
bonding.
- 15 6. A chip type semiconductor device as set forth in claim 1,  
wherein said conductive post comprises a conductive member  
which is formed by plating.
- 20 7. A chip type semiconductor device as set forth in claim 1,  
wherein said conductive post comprises a conductive member  
which is formed by using conductive adhesive.
- 25 8. A chip type semiconductor device as set forth in claim 1,  
wherein said first and second conductive land areas are formed  
by a common conductive land portion which is partitioned by a  
resist film into said first and second conductive land areas.
- 30 9. A chip type semiconductor device as set forth in claim 1,  
wherein said external electrode electrically coupled with said  
semiconductor pellet is a flat board shaped conductive member

joined onto said electrode of said semiconductor pellet.

10. A chip type semiconductor device as set forth in claim 1,  
wherein said external electrode electrically coupled with said  
5 semiconductor pellet is a hemispherical conductive member  
joined onto said electrode of said semiconductor pellet.

11. A chip type semiconductor device as set forth in claim 1,  
wherein said second conductive land area has a concave portion  
10 in which said semiconductor pellet is mounted.

12. A method of manufacturing a chip type semiconductor  
device comprising:

preparing an insulating substrate;

15 forming first and second conductive land areas on said  
insulating substrate, said first and second conductive land  
areas being electrically coupled with each other;

forming a conductive post on said first conductive land  
area;

20 mounting a semiconductor pellet which has electrodes on  
both sides thereof on said second conductive land area, said  
electrode on one side of said semiconductor pellet being coupled  
onto said second conductive land area and said electrode on the  
other side of said semiconductor pellet having an external  
25 electrode electrically coupled thereto; and

encapsulating a main area of said insulating substrate  
including said conductive post and said semiconductor pellet  
with an encapsulation resin portion, wherein top portions of  
said conductive post and said external electrode electrically  
30 coupled to said semiconductor pellet being exposed from said

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13. A method of manufacturing a chip type semiconductor device as set forth in claim 12, wherein said conductive post and said external electrode electrically coupled to said semiconductor pellet are disposed such that top surfaces of said conductive post and said external electrode become approximately coplanar with each other.

15. A method of manufacturing a chip type semiconductor device as set forth in claim 12, wherein said conductive post is a column shaped conductive block member and, in said forming a  
20 conductive post on said first conductive land area, said column shaped conductive block member is coupled to said first conductive land area by using ultrasonic bonding.

17. A method of manufacturing a chip type semiconductor  
device as set forth in claim 12, wherein said conductive post is  
30 formed by using conductive adhesive.

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